PCN# : P5B8AAB
Issue Date : Mar. 18, 2016

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product :Jun. 16, 2016

Expected First Date Code of Changed Product :1625

Description of Change (From) :
TO247_4L manufacturing using High Pb solder and Cu DAP leadframe.

Description of Change (To) :
TO247_4L manufacturing using Pb free solder(Sn80Ag20) and Ni DAP leadframe.

Reason for Change:
To comply with RoHS requirements

Affected Product(s):

FGH40T120SMDL4		

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20150440	FGH40T120SMDL4	TO247-4L	FS2 Trench IGBT	1

Test Description:	**Condition:**	**Standard:**	**Duration:**	**Results:**
Unbias Highly Accelerated Stress Test	130C, 85%	JESD22-A118	96 hrs	0/231
Temperature Cycle	-65C to 150C, 30min/cycle	JESD22-A104	500 cyc	0/77
Power Cycle	125°C T_{JC}, delta Tj of 100 C, 2.0 min on/ 2 min off	MIL-STD-750 M1037	6000 cyc	0/77
Solder Dip (Resistance to Solder Heat)	270C	JESD22-B106	15 sec	0/30